	Layer Name F.Silkscreen F.Paste F.Mask F.Cu Dielectric In1.Cu Dielectric In2.Cu Dielectric B.Cu B.Mask B.Paste	Top Silk Screen Top Solder Paste Top Solder Mask copper prepreg copper core copper prepreg copper	FR4 FR4	0 mils 0.3937007874 mils 2.8 mils	Not specified  Not specified  Not specified	1 1 3.3 1 4.5 1 4.5	Loss Tangent
			Not specified		White	1	0
	Drill Map:  * 0.635mm / 0.0250" (32 holes)  o 1.270mm / 0.0500" (0 holes + 2 slots)  + 3.658mm / 0.1440" (2 holes)  □ 5.000mm / 0.1969" (2 holes) (not plated)  **BOARD CHARACTERISTICS						
×××× ×××× ×××× ××××	BOARD CH	IARACTERISTICS		ot plated)			
10.9 mm 20.1 mm	Copper Layer	r Count: 4	, ,	Board Thic	ckness: 60.	.00 mils	
	Copper Layer	r Count: 4 al dimensions: 1636. bacing: 0.00 r h: HAL S pads: No	00 mils x 1330 nils / 20.00 n	Board Thio 2.00 mils Min hole o Impedance	ckness: 60. diameter: 11. e Control: No ard Edge: No	.81 mils	
10.9 mm 20.1 mm	Copper Layer Board overal Min track/sp Copper Finis Castellated p	r Count: 4 all dimensions: 1636.4 bacing: 0.00 r h: HAL S pads: No connectors: No  Spartan Robot Sheet: File: kraken-p	00 mils x 1330 mils / 20.00 m nPb  cics	Board Thio 0.00 mils  Nils Min hole of Impedance Plated Bo	diameter: 11. e Control: No	.81 mils	
10.9 mm 20.1 mm	Copper Layer Board overal Min track/sp Copper Finis Castellated p	r Count: 4 all dimensions: 1636.4 bacing: 0.00 r h: HAL S pads: No connectors: No  Spartan Robot Sheet: File: kraken-p	00 mils x 1330 nils / 20.00 n nPb	Board Thio 0.00 mils  Nils Min hole of Impedance Plated Bo	diameter: 11. e Control: No	81 mils	Rev: 1